



3.3V CMOS 20-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS AND BUS-HOLD

IDT74ALVCH16841

FEATURES:

- 0.5 MICRON CMOS Technology
- Typical $t_{SK(0)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015;
 > 200V using machine model ($C = 200\text{pF}$, $R = 0$)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP,
 and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to $+85^\circ\text{C}$
- $V_{CC} = 3.3V \pm 0.3V$, Normal Range
- $V_{CC} = 2.7V$ to $3.6V$, Extended Range
- $V_{CC} = 2.5V \pm 0.2V$
- CMOS power levels ($0.4\mu\text{W}$ typ. static)
- Rail-to-Rail output swing for increased noise margin

Drive Features for ALVCH16841:

- High Output Drivers: $\pm 24\text{mA}$
- Suitable for heavy loads

APPLICATIONS:

- 3.3V High Speed Systems
- 3.3V and lower voltage computing systems

DESCRIPTION:

This 20-bit interface D-type latch is built using advanced dual metal CMOS technology. The ALVCH16841 features 3-state outputs designed

specifically for driving highly capacitive relatively low-impedance loads. This device is particularly suitable for implementing buffer registers, unidirectional bus drivers, and working registers.

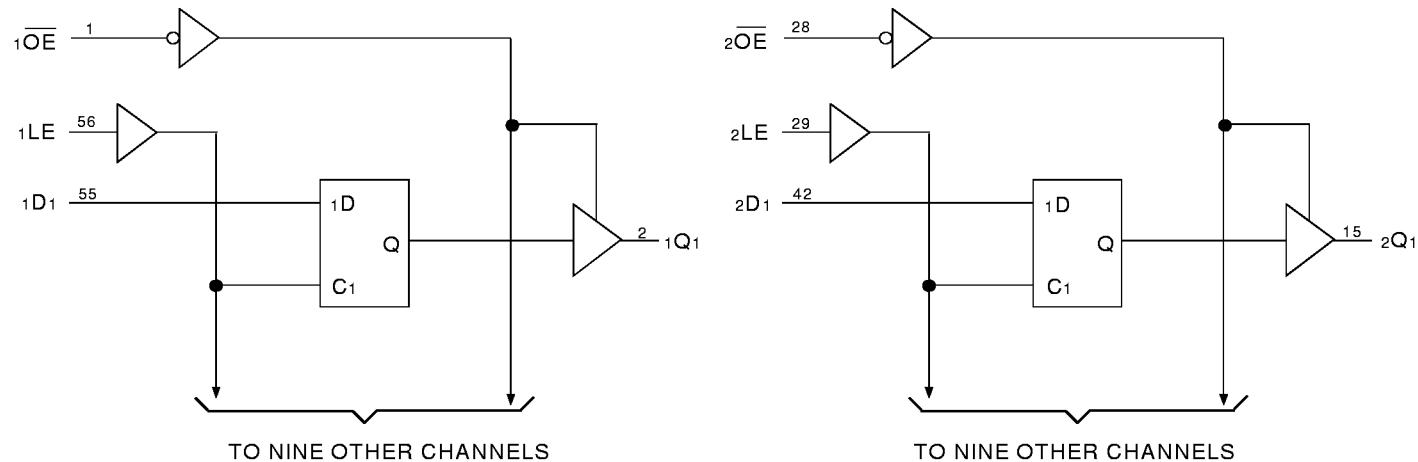
The ALVCH16841 can be used as two 10-bit latches or one 20-bit latch. The 20 latches are transparent D-type latches. The device has noninverting data (D) inputs and provides true data at its outputs. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the D inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable ($1\overline{OE}$ or $2\overline{OE}$) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. \overline{OE} does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The ALVCH16841 has been designed with a $\pm 24\text{mA}$ output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

The ALVCH16841 has "bus-hold" which retains the inputs' last state whenever the input bus goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

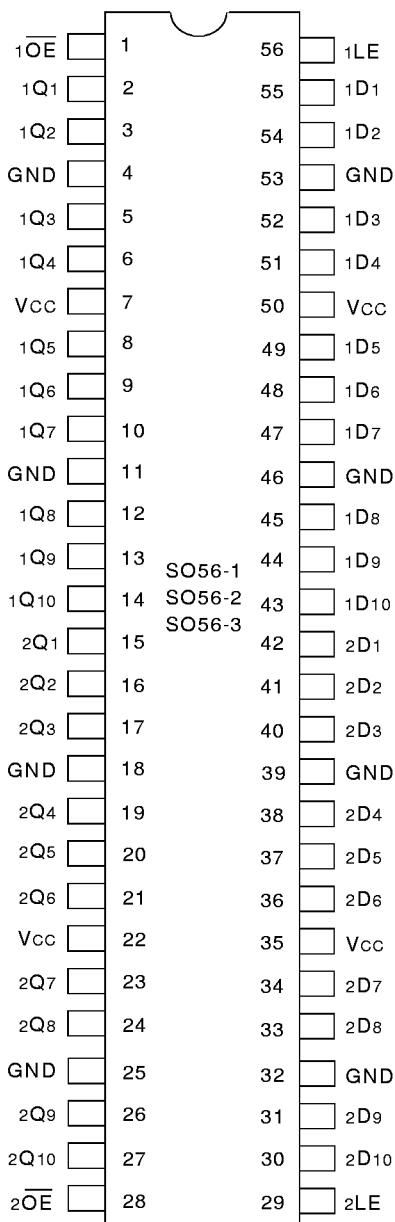
Functional Block Diagram



EXTENDED COMMERCIAL TEMPERATURE RANGE

MARCH 1999

PIN CONFIGURATION



SSOP/
TSSOP/TVSOP
TOP VIEW

PIN DESCRIPTION

Pin Names	Description
xDx	Data Inputs ⁽¹⁾
xLE	Latch Enable Inputs (Active HIGH)
xOE	Output Enable Inputs (Active LOW)
xQx	3-State Outputs

NOTE:

- These pins have "Bus-Hold." All other pins are standard inputs, outputs, or I/Os.

ABSOLUTE MAXIMUM RATING (1)

Symbol	Description	Max.	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	- 0.5 to + 4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	- 0.5 to Vcc + 0.5	V
TSTG	Storage Temperature	- 65 to + 150	°C
I _{OUT}	DC Output Current	- 50 to + 50	mA
I _{IK}	Continuous Clamp Current, V _I < 0 or V _I > Vcc	± 50	mA
I _{OK}	Continuous Clamp Current, V _O < 0	- 50	mA
I _{CC}	Continuous Current through each Vcc or GND	± 100	mA
I _{SS}			

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NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- Vcc terminals.
- All terminals except Vcc.

CAPACITANCE ($T_A = +25^\circ\text{C}$, $f = 1.0\text{MHz}$)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	5	7	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	7	9	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	7	9	pF

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NOTE:

- As applicable to the device type.

FUNCTION TABLE (each 10-bit latch) (1)

Inputs		Outputs	
xDx	xLE	xOE	xQx
H	H	L	H
L	H	L	L
X	L	L	Q ₀
X	X	H	Z

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
- Q_0 = Level of Q before the indicated steady-state input conditions were established.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = -40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
VIH	Input HIGH Voltage Level	Vcc = 2.3V to 2.7V		1.7	—	—	V
		Vcc = 2.7V to 3.6V		2	—	—	
VIL	Input LOW Voltage Level	Vcc = 2.3V to 2.7V		—	—	0.7	V
		Vcc = 2.7V to 3.6V		—	—	0.8	
I _{IH}	Input HIGH Current	Vcc = 3.6V	Vi = Vcc	—	—	± 5	µA
I _{IL}	Input LOW Current	Vcc = 3.6V	Vi = GND	—	—	± 5	µA
I _{OZH}	High Impedance Output Current (3-State Output pins)	Vcc = 3.6V	Vo = Vcc	—	—	± 10	µA
I _{OZL}			Vo = GND	—	—	± 10	µA
V _{IK}	Clamp Diode Voltage	Vcc = 2.3V, I _{IN} = -18mA		—	-0.7	-1.2	V
V _H	Input Hysteresis	Vcc = 3.3V		—	100	—	mV
I _{CCL} I _{CCH} I _{CCZ}	Quiescent Power Supply Current	Vcc = 3.6V VIN = GND or Vcc		—	0.1	40	µA
ΔI _{CC}	Quiescent Power Supply Current Variation	One input at Vcc - 0.6V, other inputs at Vcc or GND		—	—	750	µA

NOTE:

1. Typical values are at Vcc = 3.3V, +25°C ambient.

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BUS-HOLD CHARACTERISTICS

Symbol	Parameter ⁽¹⁾	Test Conditions		Min.	Typ. ⁽²⁾	Max.	Unit
I _{BHH}	Bus-Hold Input Sustain Current	Vcc = 3.0V	Vi = 2.0V	-75	—	—	µA
			Vi = 0.8V	75	—	—	
I _{BHH}	Bus-Hold Input Sustain Current	Vcc = 2.3V	Vi = 1.7V	-45	—	—	µA
			Vi = 0.7V	45	—	—	
I _{BHHO} I _{BHLO}	Bus-Hold Input Overdrive Current	Vcc = 3.6V	Vi = 0 to 3.6V	—	—	± 500	µA

NOTES:

1. Pins with Bus-hold are identified in the pin description.
2. Typical values are at Vcc = 3.3V, +25°C ambient.

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OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	Vcc = 2.3V to 3.6V	I _{OH} = -0.1mA	Vcc - 0.2	—	V
		Vcc = 2.3V	I _{OH} = -6mA	2	—	
		Vcc = 2.3V	I _{OH} = -12mA	1.7	—	
		Vcc = 2.7V		2.2	—	
		Vcc = 3.0V		2.4	—	
		Vcc = 3.0V	I _{OH} = -24mA	2	—	
VOL	Output LOW Voltage	Vcc = 2.3V to 3.6V	I _{OL} = 0.1mA	—	0.2	V
		Vcc = 2.3V	I _{OL} = 6mA	—	0.4	
			I _{OL} = 12mA	—	0.7	
		Vcc = 2.7V	I _{OL} = 12mA	—	0.4	
		Vcc = 3.0V	I _{OL} = 24mA	—	0.55	

NOTE:

1. V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{cc} range. T_A = -40°C to +85°C.

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OPERATING CHARACTERISTICS, T_A = 25°C

Symbol	Parameter	Test Conditions	Vcc = 2.5V ± 0.2V	Vcc = 3.3V ± 0.3V	Unit
			Typical	Typical	
CPD	Power Dissipation Capacitance Outputs enabled	CL = 0pF, f = 10Mhz	12	20	pF
	Power Dissipation Capacitance Outputs disabled		1	3	

SWITCHING CHARACTERISTICS⁽¹⁾

Symbol	Parameter	Vcc = 2.5V ± 0.2V		Vcc = 2.7V		Vcc = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
tPLH tPHL	Propagation Delay xDx to xQx	1	5	—	4.7	1.2	3.9	ns
tPLH tPHL	Propagation Delay xLE to xQx	1	5.6	—	5.1	1	4.3	ns
tPZH tPZL	Output Enable Time xOE to xQx	1	6.2	—	6	1	4.9	ns
tPHZ tPLZ	Output Disable Time xOE to xQx	1.1	5.3	—	4.3	1.3	4.1	ns
tsU	Setup Time, data before LE↓	0.9	—	0.7	—	1.1	—	ns
t _H	Hold Time, data after LE↓	1.2	—	1.5	—	1.1	—	ns
t _W	Pulse Duration, LE HIGH	3.3	—	3.3	—	3.3	—	ns
tsk(o)	Output skew ⁽²⁾	—	—	—	—	—	500	ps

NOTES:

1. See test circuits and waveforms. T_A = -40°C to +85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

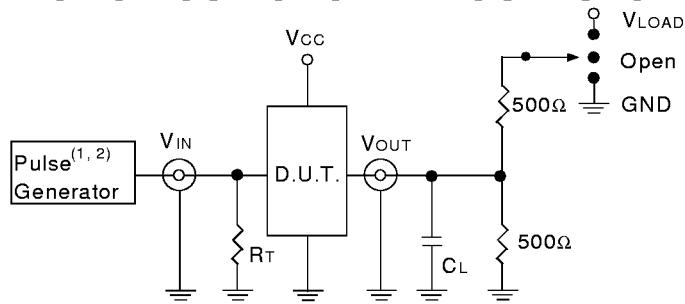
TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	$V_{CC(1)} = 3.3V \pm 0.3V$	$V_{CC(1)} = 2.7V$	$V_{CC(2)} = 2.5V \pm 0.2V$	Unit
V_{LOAD}	6	6	$2 \times V_{CC}$	V
V_{IH}	2.7	2.7	V_{CC}	V
V_T	1.5	1.5	$V_{CC}/2$	V
V_{LZ}	300	300	150	mV
V_{HZ}	300	300	150	mV
C_L	50	50	30	pF

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TEST CIRCUITS FOR ALL OUTPUTS



DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

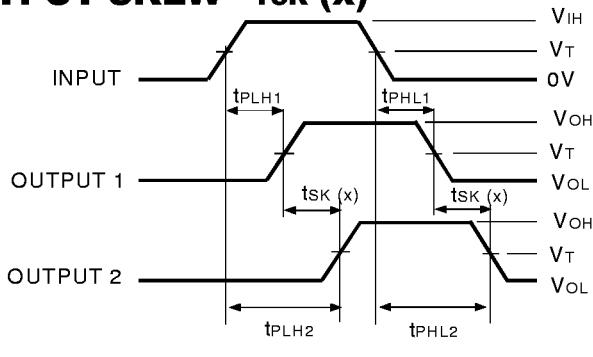
1. Pulse Generator for All Pulses: Rate $\leq 10\text{MHz}$; $t_F \leq 2.5\text{ns}$; $t_R \leq 2.5\text{ns}$.
2. Pulse Generator for All Pulses: Rate $\leq 10\text{MHz}$; $t_F \leq 2\text{ns}$; $t_R \leq 2\text{ns}$.

SWITCH POSITION

Test	Switch
Open Drain	V_{LOAD}
Disable Low	
Enable Low	GND
Disable High	
Enable High	
All Other tests	Open

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OUTPUT SKEW - $tsk(x)$



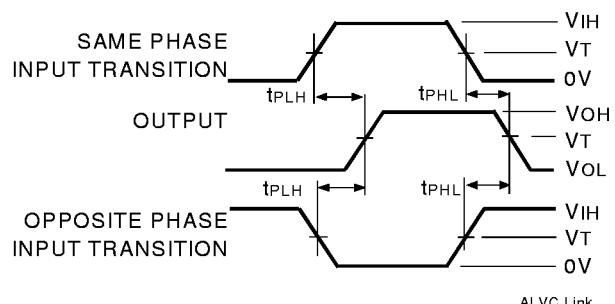
$$tsk(x) = |tPLH2 - tPLH1| \text{ or } |tPHL2 - tPHL1|$$

ALVC Link

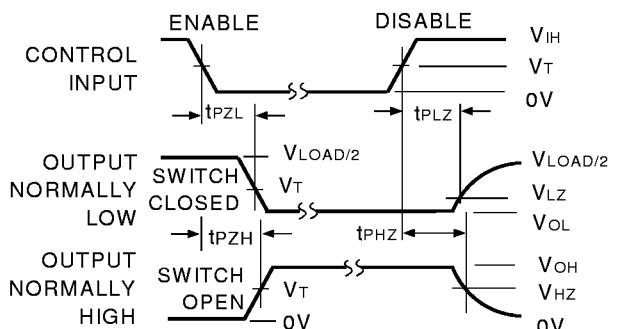
NOTES:

1. For $tsk(o)$ OUTPUT1 and OUTPUT2 are any two outputs.
2. For $tsk(b)$ OUTPUT1 and OUTPUT2 are in the same bank.

PROPAGATION DELAY



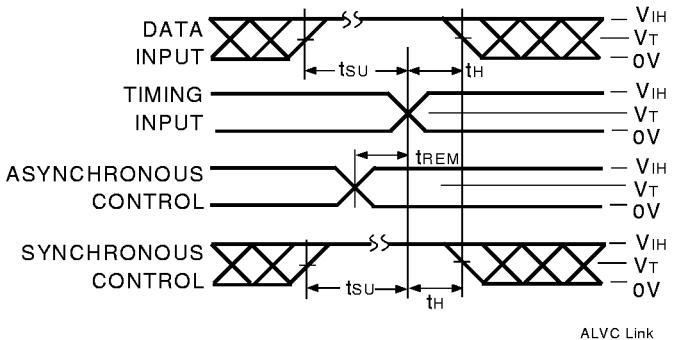
ENABLE AND DISABLE TIMES



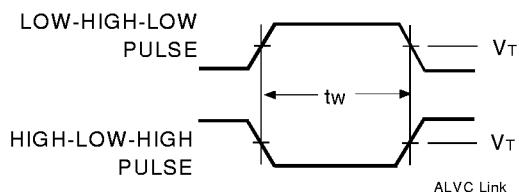
NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



PULSE WIDTH



ORDERING INFORMATION

IDT XX ALVC X XXX XXX XX

Temp. Range Bus-Hold Family Device Type Package

- PV Shrink Small Outline Package (SO56-1)
- PA Thin Shrink Small Outline Package (SO56-2)
- PF Thin Very Small Outline Package (SO56-3)
- 841 20-Bit Bus-Interface D-Type Latch with 3-State Outputs
- 16 Double-Density with Resistors, $\pm 24\text{mA}$
- H Bus-Hold
- 74 -40°C to $+85^\circ\text{C}$



CORPORATE HEADQUARTERS
2975 Stender Way
Santa Clara, CA 95054

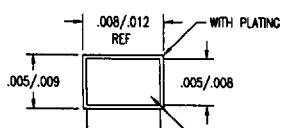
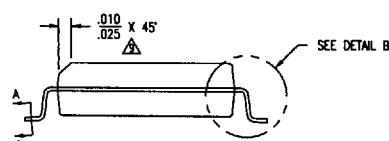
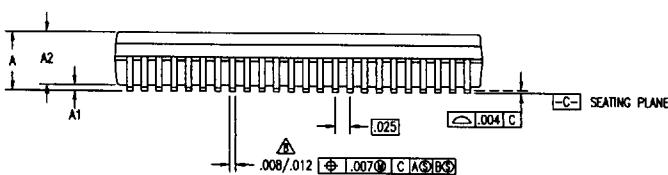
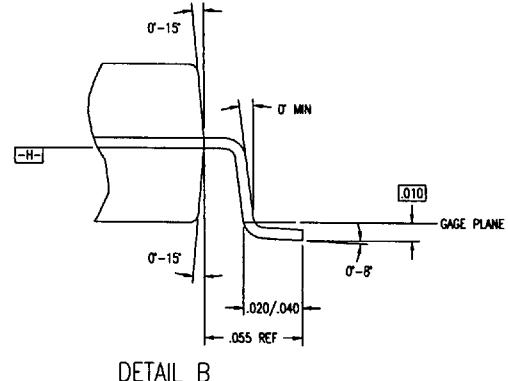
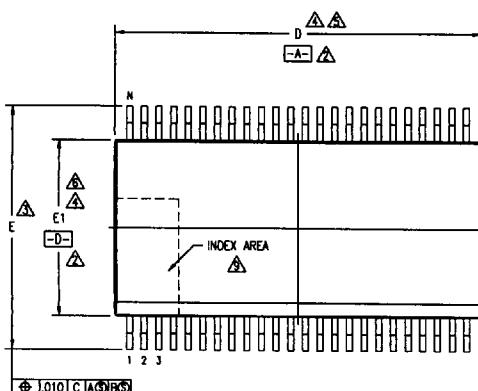
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PACKAGE DIAGRAM OUTLINES

SSOP

REVISED				
DOC	REV	DESCRIPTION	DATE	APPROVED
17693	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. VU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	



SECTION A-A

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Slander Way, Santa Clara, CA 95054	
DECIMAL	ANGULAR	PHONE: (408) 727-9118	FAX: (408) 492-9674
X0.0±	±	TWX: 910-338-2070	
X0.0±			
ROCKE			
APPROVALS	DATE	TITLE PV PACKAGE OUTLINE	
DRAWN <i>ad</i>	08/15/90	.300" BODY WIDTH SSOP	
CHECKED		.025" PITCH	
		SIZE	DRAWING NO.
		C	PSC-4029
		DO NOT SCALE DRAWING	

■ 4825771 0021981 OTO ■

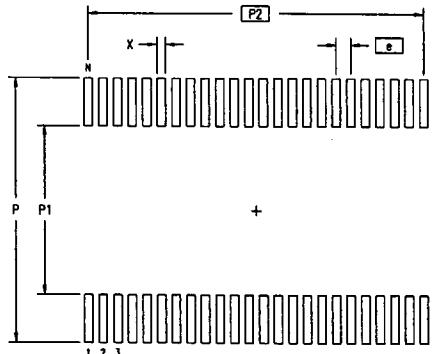
112

PACKAGE DIAGRAM OUTLINES
SSOP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. VU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

DWG #			SO48-1			DWG #			SO56-1		
SYMBOL	JEDEC VARIATION			NOTE	JEDEC VARIATION			NOTE	JEDEC VARIATION		
	AA	AB	AC		AB	AC	AD		AE	AF	AI
L	MIN	NOM	MAX		MIN	NOM	MAX		MIN	NOM	MAX
A	.095	.102	.110		.095	.102	.110		.095	.102	.110
A1	.008	.012	.016		.008	.012	.016		.008	.012	.016
A2	.088	.090	.092		.088	.090	.092		.088	.090	.092
D	.620	.625	.630	4.5	.720	.725	.730	4.5	.720	.725	.730
E	.395	.405	.420	3	.395	.405	.420	3	.395	.405	.420
E1	.291	.295	.299	4.6	.291	.295	.299	4.6	.291	.295	.299
N	48				56				48		

LAND PATTERN DIMENSIONS



NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- 2 DATUMS $-A-$ AND $-B-$ TO BE DETERMINED AT DATUM PLANE $-H-$
- 3 DIMENSION E TO BE DETERMINED AT SEATING PLANE $-C-$
- 4 DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE $-H-$
- 5 DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE
- 6 DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .015 PER SIDE
- 7 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP
- 8 LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- 9 THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED
- 10 ALL DIMENSIONS ARE IN INCHES
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-118, VARIATION AA & AB

	MIN	MAX	MIN	MAX
P	.450	.458	.450	.458
P1	.282	.290	.282	.290
P2	.575 BSC		.675 BSC	
X	.010	.018	.010	.018
e	.025 BSC		.025 BSC	
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Sandier Way, Santa Clara, CA 95054 PHONE: (408) 727-8116 FAX: (408) 482-8874 TWX: 810-338-2070	
DECIMAL	ANGULAR		
.005	\pm		
.005			
.005			
APPROVALS		DATE	TITLE
DRAWN <i>ad</i>		06/15/90	PV PACKAGE OUTLINE
CHECKED			.30° BODY WIDTH SSOP
			.025° PITCH
SIZE		DRAWING NO.	REV
C		PSC-4029	02
DO NOT SCALE DRAWING			

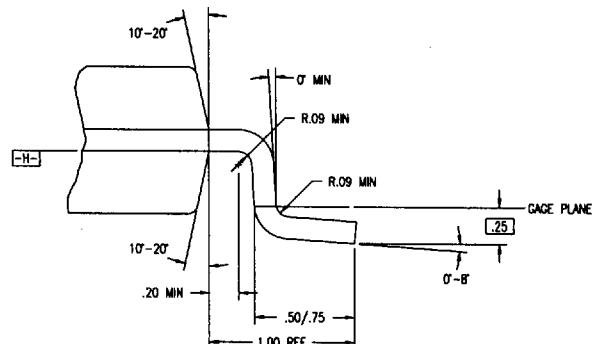
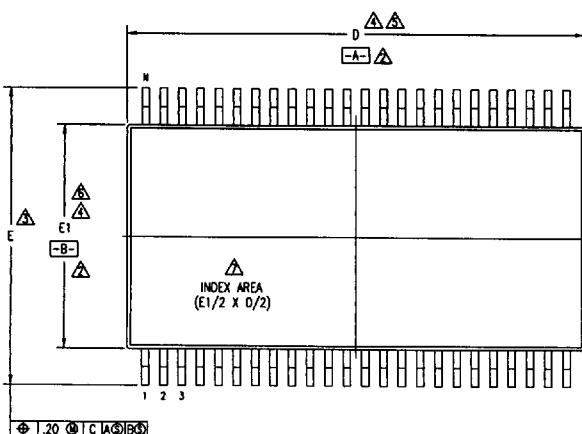
■ 4825771 0021982 T37 ■

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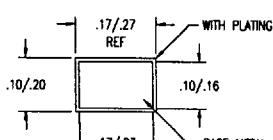
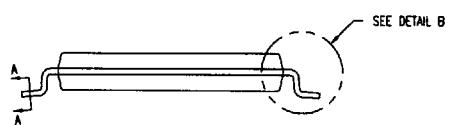
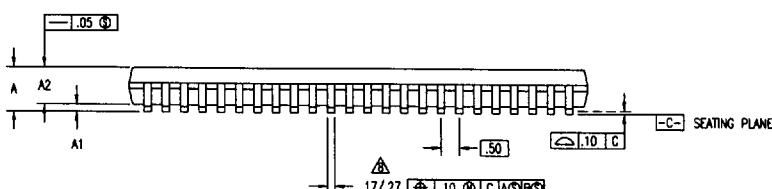
PACKAGE DIAGRAM OUTLINES

TSSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	



DETAIL B



SECTION A-A

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Sander Way, Santa Clara, CA 95054 PHONE: (408) 727-8116 FAX: (408) 492-5674 TELC: 910-338-2070		
RADIAL ANGULAR XX-X XXX-X XXXX-X				
APPROVALS	DATE			
DRAWN	44	6.10 mm BODY WIDTH TSSOP		
CHECKED		.50 mm PITCH		
		SIZE	DRAWING No.	REV
		C	PSC-4039	03
DO NOT SCALE DRAWING				

■ 4825771 0021991 T4T ■

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PACKAGE DIAGRAM OUTLINES

TSSOP (Continued)

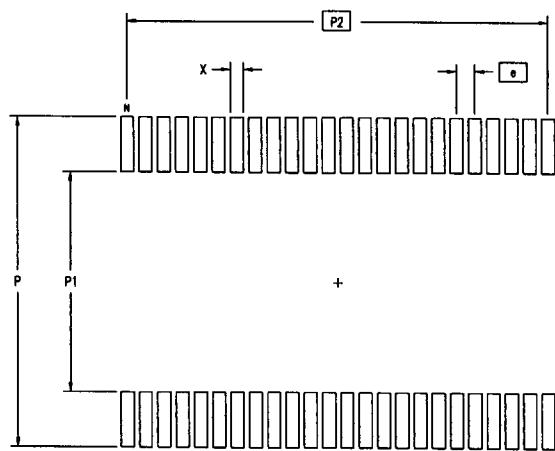
DWG #			S048-2			DWG #			S056-2		
S Y M B O	JEDEC VARIATION			N O T E	JEDEC VARIATION			N O T E	JEDEC VARIATION		
	ED	EE	EE		MIN	NOM	MAX		MIN	NOM	MAX
A	—	—	1.10		—	—	1.10		—	—	1.10
A1	.05	—	.15		.05	—	.15		.05	—	.15
A2	.85	1.00	1.05		.85	1.00	1.05		.85	1.00	1.05
D	12.40	12.50	12.60	4.5	13.90	14.00	14.10	4.5	13.90	14.00	14.10
E	7.95	8.10	8.25	3	7.95	8.10	8.25	3	7.95	8.10	8.25
E1	6.00	6.10	6.20	4.6	6.00	6.10	6.20	4.6	6.00	6.10	6.20
N	48				56						

NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- ⚠ DATUMS **(-A-)** AND **(-B-)** TO BE DETERMINED AT DATUM PLANE **(-H-)**
- ⚠ DIMENSION E TO BE DETERMINED AT SEATING PLANE **(-C-)**
- ⚠ DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE **(-H-)**
- ⚠ DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- ⚠ DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- ⚠ DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- ⚠ LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- ⚠ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION ED & EE

REVISIONS			
DCN	REV	DESCRIPTION	DATE APPROVED
23757	00	INITIAL RELEASE	02/15/93 T. YU
26315	01	CHANGE DIMS A1 & A2	05/18/94 DG
26490	02	CHANGE DIM A1	07/21/94 T. YU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX
P	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10
P2	11.50	BSC	13.50	BSC
X	.30	.40	.30	.40
e	.50	BSC	.50	BSC
N	48			56

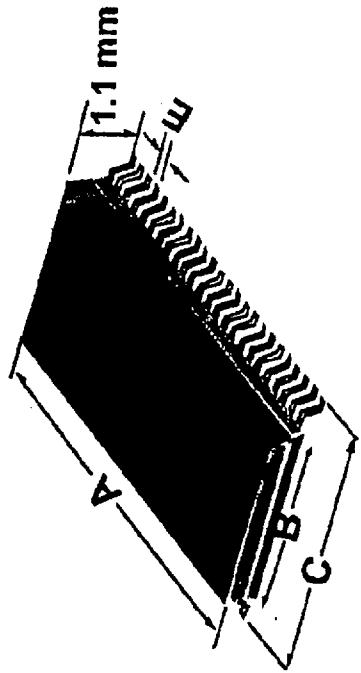
TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Sandier Way, Santa Clara, CA 95054	
DECIMAL INCHES	ANGULAR DEGREES	<i>dt</i> PHONE: (408) 727-6118 FAX: (408) 482-8874 TWX: 910-338-2070	
± .004 .00256	± .004 .00256		
APPROVALS	DATE	TITLE PA PACKAGE OUTLINE 6.10 mm BODY WIDTH TSSOP .50 mm PITCH	
DRAWN <i>ad</i>	01/19/93		
CHECKED			
		SIZE	DRAWING No.
		C	PSC-4039
			REV 03
		DO NOT SCALE DRAWING	

■ 4825771 0021992 986 ■

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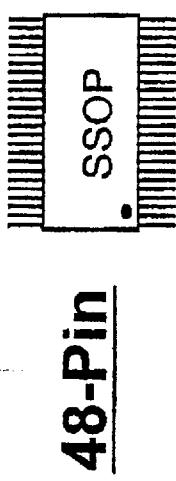
TVSOP

The Most Compact Double Density Package

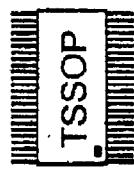


TVSOP Package	Typical Dimensions (in mm)			Area (mm ²)
	A	B	C	E
48 Pin	9.80	4.40	6.40	0.40
56 Pin	11.30	4.40	6.40	0.40
80 Pin	17.00	6.10	8.10	0.40
100 Pin	20.80	6.10	8.10	0.40

Double Density Packaging



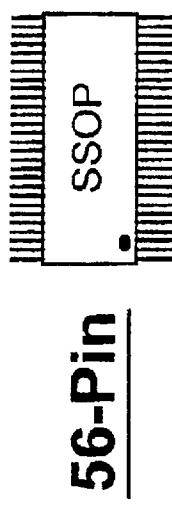
**16.0 x 10.3 x 2.6 mm
pin pitch = 0.635 mm
Area = 164.8 mm²**



**12.5 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 101.3 mm²**



**9.8 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 62.7 mm²**



**18.4 x 10.3 x 2.6 mm
pin-pitch = 0.635 mm
Area = 189.5 mm²**



**14.0 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 113.4 mm²**



**11.3 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 72.3 mm²**

TVSOP	Area (mm ²)	% Smaller Than SSOP	% Smaller Than TSSOP
48 pin	63.00	61.9	38.0
56 pin	72.30	62.2	36.0